Integration Issues in Micro-Optical Systems for Ion Trap Quantum Computation



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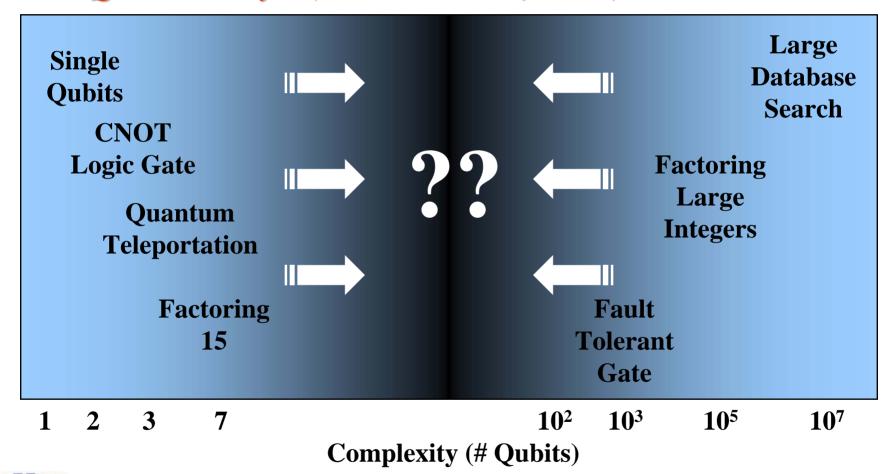
Outline

- Introduction
- Technology Example of Complex Optical Systems
 - Lucent LambdaRouterTM
- Process Engineering Complex Systems
- Example Scalable State Measurement
- Outlook



"Transistor to Processor"

• Quantum Abyss (Dave Wineland, NIST)





Bridging the Gap

• The History of Integrated Circuits

- ...(ICs are) made from different electrical components such as *transistors*, *resistors*, *capacitors* and *diodes*, that are *connected* to each other in different ways...
- First Integrated Circuit (Kilby & Noyce, 1958)
- "...reduce the cost of electronic functions by a factor of a million to one, nothing had ever done that..." Kilby

http://nobelprize.org/physics/educational/integrated_circuit/history/

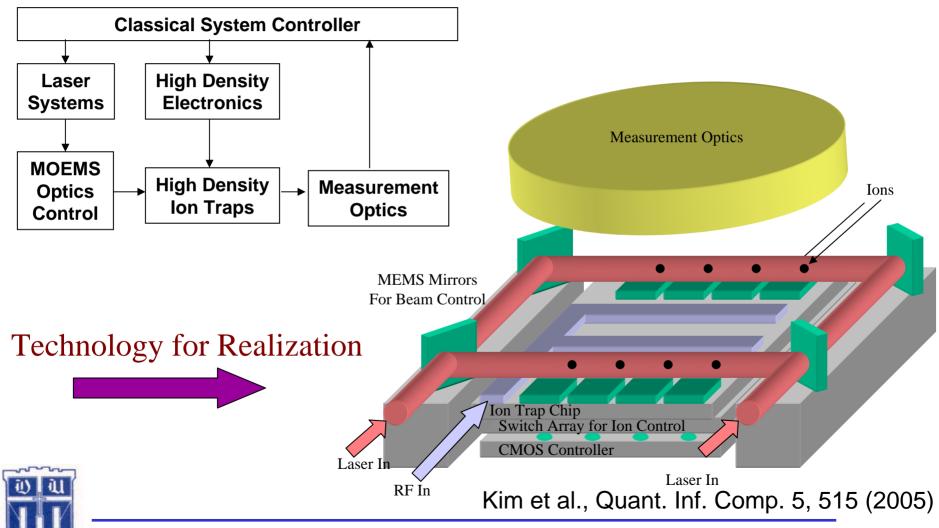
• Good integration technology

- Capability to integrate ALL ELEMENTS required
- Each element integration approach has to be scalable
- For ion trap QC, this includes traps, ion motion control, laser sources, beam delivery, state detection, quantum state transfer (wires) and classical control



Technology for Scaling Ion Traps

Elements of Ion Trap Quantum Computer



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The Bell Labs Team

MEMS Devices

Vladimir Aksyuk Susanne Arney Dustin Carr Ho Bun Chan **Arman Gasparyan Dennis Greywall Martin Haueis** Victor Lifton Flavio Pardo Herb Shea Maria E. Simon **Alex Tran** SLIMLine Team SFRL Team **Systems**

Optics/Mechanics

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Robert Boie **Robert Frahm John Gates Rick Papazian** Rene Ruel

Subsystems Research

Anatoli Olkhovets Mischa Kozhevnikov **Dong Jae Shin** John Weld **Chuck Lichtenwalner**

Device Packaging

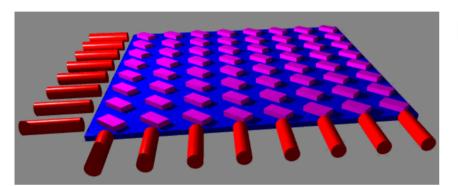
Chia Chang Richard George David Ramsey Yee Low





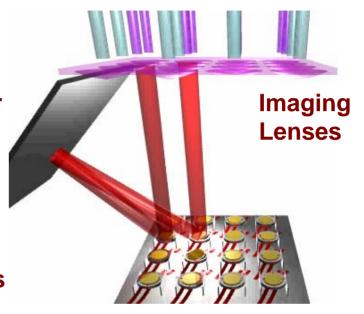
Lucent LambdaRouterTM All Optical Switch

2D vs. 3D Switching Architecture



I/O SM Fibers

Reflector



MEMS 2-axis Tilt Mirrors

Pros: Only feasible Technology to scale to Large Portcount

- Number of devices needed scales as 2N
- Overall system yield robust to device yield

Proper design eliminates path length-dependent loss

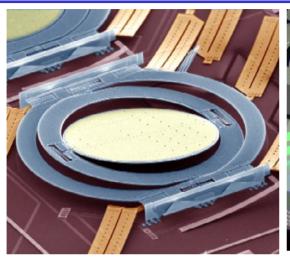
Cons: Switch complexity is in analog control of mirror tilts

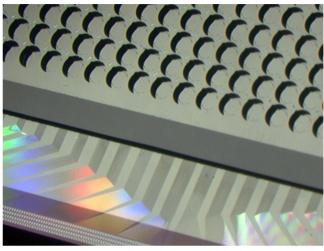
- N² conditions for all possible connections





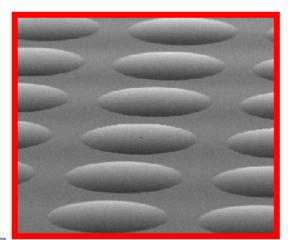
Critical Components – Optical MEMS

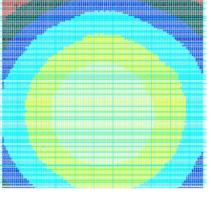


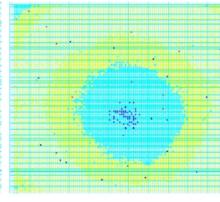


Surface Micromachined Mirror

Bulk Micromachined Mirror







Focal Length Map

Insertion Loss Map



Focal Length Target +/- 3 %, Insertion Loss 0.1- 0.3dB (~10K/wafer)

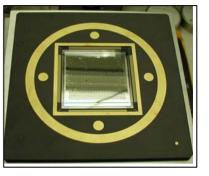
1296x1296 Optical Switch



One of the most complex optical systems!!







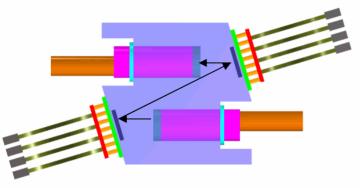
- -5184 chip IOs
- **-2592 fibers**
- -1296 laser beams
- -10,368 HV DACs
- -1296 photodetectors
- -1,679,616 **possible states**
- -Advanced control
- -Optimization Algorithms



J. Kim et al., IEEE PTL 15, p 1537 (2003)

1296 System in Action

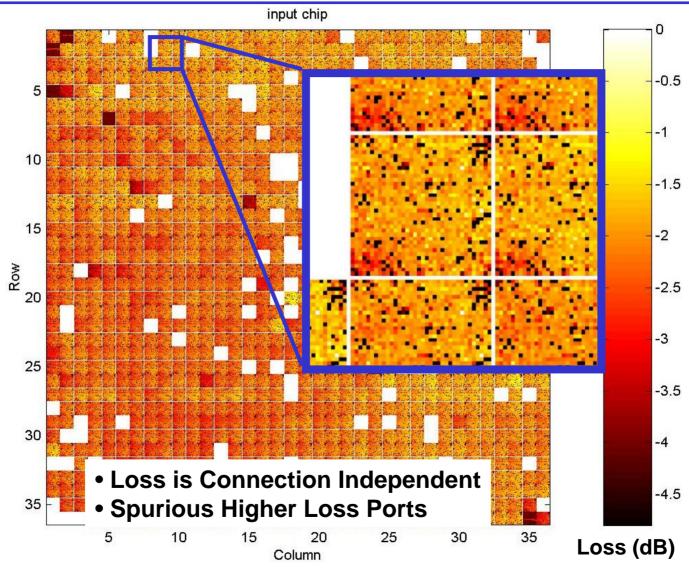
• Precision control of mirror position to establish connections







Largest Non-blocking OXC







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Switch Fabric Design Considerations

• System design is multi-dimensional optimization problem - Starting from requirements, constrained by technology!! **Packaging** Reliability **Fabrication Software MEMS** Design Curvature Resolution Requirements **Angular** Design Max. Volt. **Portcount** Range Loss **System Operation** Circuit **Optical Vibration** Design **Environment Design** Design Shock Etc. Thermal **Testset** Mechanical **Mechanical** Design **Stability** Design **Switch Fabric** Design

MEMS Technology Adaptation for Ion Traps

• Optical Communication Technology provides

- Platform for high density, high functionality optical systems
- Challenge is tailoring the technology for ion trap QCs

• Optical Functionality

- What functions should be implemented using micro-optics?
- Analysis of tolerance, operation speed, etc.

• Operational Requirements

- UV wavelength operation
- Power handling capability
- Polarization maintenance

• Vacuum Compatibility?

- Mirror cooling
- High quality factor: ringing in mirror motion

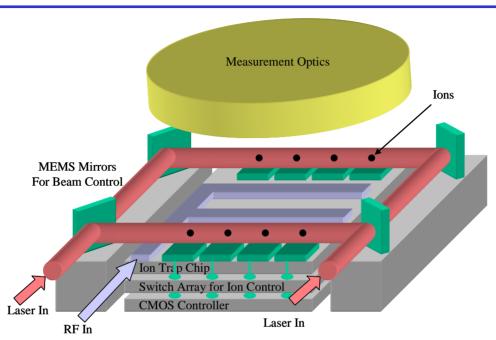


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Scalable State Measurement Problem



- Multi-zone State Measurement: Why?
 - Current solutions are considered not scalable (NIST group)
 - Optical requirements are modest while illuminating
- Two Critical Elements
 - "Pump" beam delivery to multiple zones
 - High efficiency multi-pixel photon detection



Beam Delivery - Micromirrors

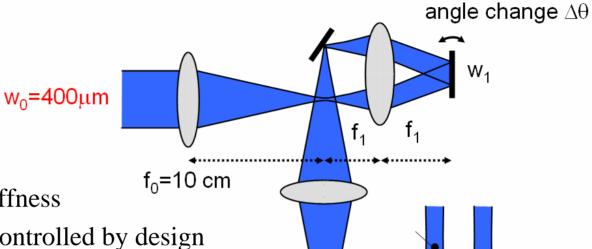
Optical Design

$$- f \sim w0 \sim r \sim 1/q$$

- Actuation Torque t
 - t ~ r3V2/g2
 - Necessary torsional stiffness
 - $k \sim t/q \sim r4V2/g2$: Controlled by design
- Mirror Moment of Inertia
 - $-I \sim mr2 \sim t \ r4$
 - Resonance frequency $f \sim (k/I)^{1/2} \sim (V2/t g2)^{1/2}$
- Conclusions: Independent of radius *r!!*

Control voltage is critical variable

• Radius is determined if we desire critical damping

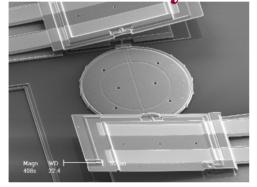


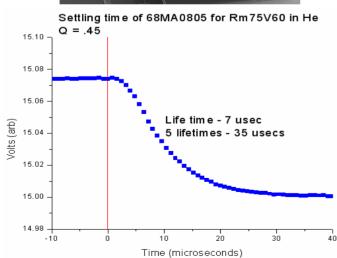
 $w_2 = 25 \mu m$

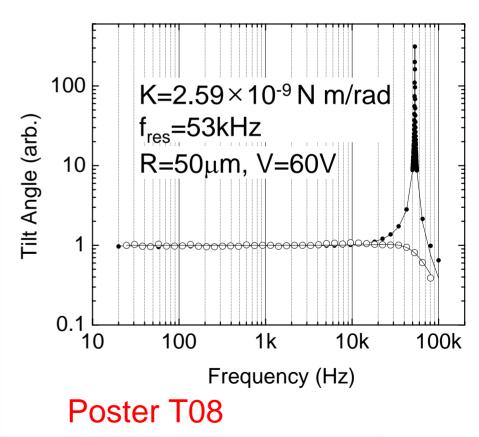
Position shift Δx=240μm

Preliminary Micromirror Performance

- Devices fabricated at foundry (MEMScAP, Inc.)
- Post-processing done at Duke
 - Mirror reflectivity ~ 70% at 313 nm



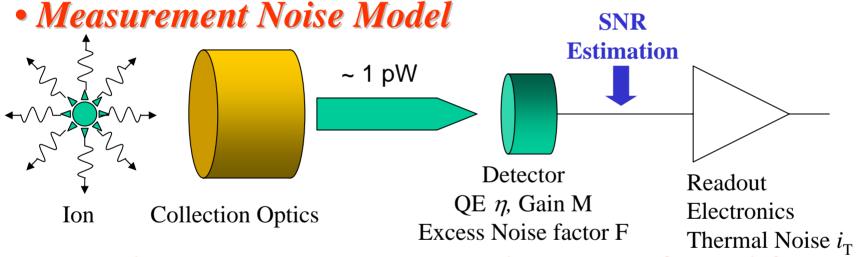






Collection Optics and Detectors

- System Requirements (D. Leibfried, NIST)
 - Single ion generates ~ 1 pW into F/# = 1 optics (~1.6M ph/s)
 - Need BER < 1% with < 200 μ s integration time



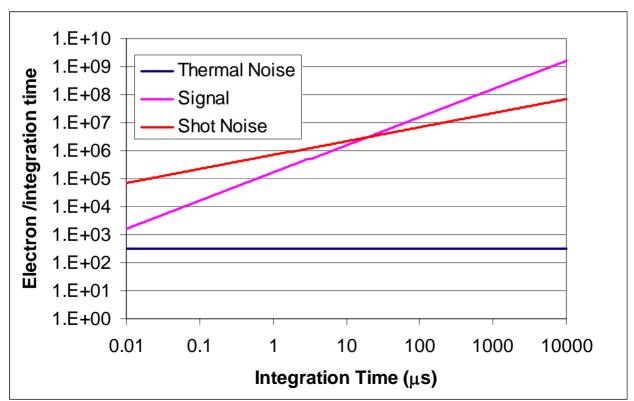
- Signal-to-noise estimation at the input of amplifier
 - Signal level affected by detector QE and gain
 - Noise contribution from signal shot noise, detector multiplication noise and amplifier thermal noise

Kim et al. Nonclassical light from semiconductor lasers and LEDs, Ch 12, Springer (2001)



Example: Photomultiplier Tube

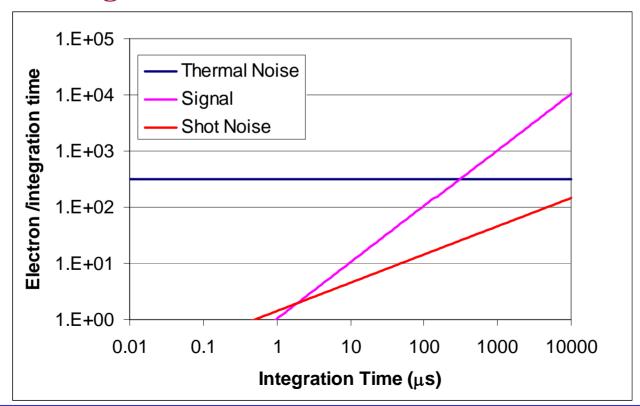
- Assumptions
 - QE of 10%, $M = 10^6$ Photon counting mode
 - SNR limited by signal shot noise, need ~9-12 detected photons to achieve 10⁻³-10⁻⁴ BER





Example: Standard CCD

- Assumptions
 - QE of 65%, No gain Charge integration mode
 - SNR limited by readout thermal noise
 - ~1 ms integration time needed

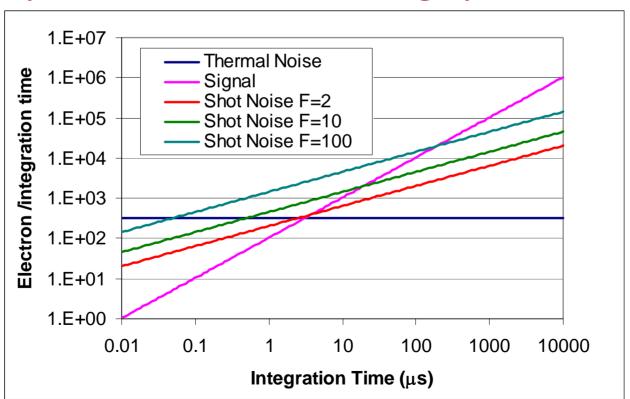




Example: Intensified CCD/APD

• Assumptions

- QE of 65%, M = 100, Charge integration mode
- SNR limited mostly by shot noise
- Variety of detectors fall in this category

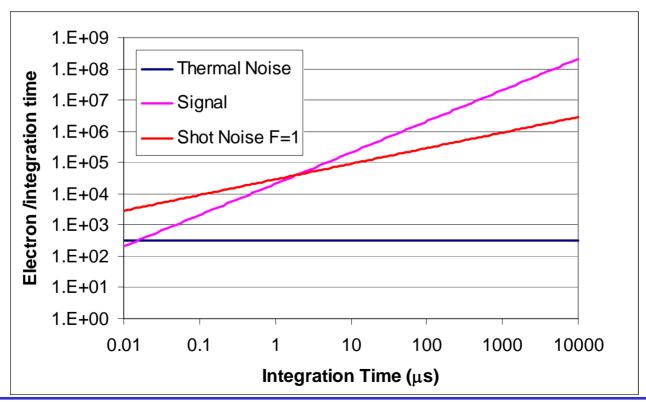




Example: "Dream" Detector

• Assumptions

- QE of 65%, arrayed, M >>1, F=1, Photon counting mode
- Too good to be true? Penalty is low temperature operation
- Integration time can be reduced to $\sim 10~\mu s$





Collection Optics Strategies

- Challenge
 - Low F/# lens has small field of view and large aberration

Use of Microlenses Conventional Approach Direct Integration Approach CCD / imaging device **Detector Array Detector Devices** (w/ micro-optics) Spacers **Conventional Optics** Ion trap chip Detector chip Or Fiber Array Flip-chip **Imaging Optics Bonding** Ion trap chip **Duke University**

Outlook

- Fully Integrated Optics?
 - Optical Integration cannot be an "after-thought"!!
 - Surface trap has LOTS of advantages...

